

SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10B224JO8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 220nF, 16V, ±5%, X7R, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>B</u> <u>224</u> <u>J</u> <u>O</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

_	Series Size	Samsung Multi-layer Co 0603 (inch code)	eramic Capa L: 1.6		W:	0.8	±0.1	mm
3	Dielectric	X7R	8	Inner electrode		Ni		
4	Capacitance	220 nF		Termination		Cu		
(5)	Capacitance	±5 %		Plating		Sn 10	0%	(Pb Free)
	tolerance		9	Product		Norma	al	
6	Rated Voltage	16 V	10	Special		Reser	ved for	future use
7	Thickness	0.8 ± 0.1 mm	11)	Packaging		Cardb	oard T	ype, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms					
Tan δ (DF)	0.035 max.						
Insulation	10,000Mohm or 100Mohm·uF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X7R						
Characterisitcs	(From -55 $^{\circ}$ to 125 $^{\circ}$, Capacitance change shoud be within \pm 15%)						
Adhesive Strength	No peeling shall be occur on the	500g⋅F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within $\pm 12.5\%$	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 95% of terminal surface	1) Sn63Pb37 solder					
	is to be soldered newly	235±5℃, 5±0.5sec.					
		2) SnAg3.0Cu0.5 solder					
		245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition				
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm				
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)				
		2hours × 3 direction (x, y, z)				
Humidity	Capacitance change: within ±12.5%	40±2℃, 90~95%RH, 500+12/-0hrs				
	Tan δ : 0.05 max					
	IR: 1000Mohm or 50Mohm · uF					
	Whichever is Smaller					
Moisture	Capacitance change: within ±12.5%	With rated voltage				
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs				
	IR: 500Mohm or 25Mohm · uF					
	Whichever is Smaller					
High Temperature	Capacitance change: within ±12.5%	With 200% of the rated voltage				
Resistance	Tan δ : 0.05 max	Max. operating temperature				
	IR: 1000Mohm or 50Mohm · uF					
	Whichever is Smaller	1000+48/-0hrs				
Temperature Capacitance change: within ±7.5		1 cycle condition				
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25°C				
		→ Max. operating temperature → 25°C				
		5 cycle test				

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 250 \pm 5 $^{\circ}$ C, 6sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.